UL Product iQ®



E469747

ZPMV2.E469747 - Wiring, Printed - Component

Wiring, Printed - Component

Shenzhen Huaqiu Electronics Co Ltd

Room 503, 5th Floor, Tianxin Building No. 46 Meilin Road Futian District Shenzhen, Guangdong 518049 China

> Cond Width Max Report Assembly Min Date Solder Solder Cond SS/ Area Surface Oper Meets C DS/ Diam After **Process Process** Temp Flame UL796 T Min Edge Thk Mount Limits 2022-Temp 01-01 Technology Type mm mic DSO mm °C Cycles °C sec °C Class **DSR** mm Multilayer printed wiring boards V-0 3 **HQPCB-**0.13 0.20 17 DS 50.8 No 288 20 130 ΑII Int:17 **HQPCB-**DS 260 2 V-0 3 0.13 0.13 17 50.8 130 ΑII Yes Yes 4(ASP Int:68 1) Single layer printed wiring boards HQPCB-0.13 50.8 130 V-0 0.2 DS No 288 20 ΑII 3 **HQPCB-**0.13 0.13 DS 50.8 Yes 260 2 130 V-0 3 17 Yes ΑII 3(ASP 1)

ASP 1 - Assembly Solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

Marking: Company nameor file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2022-06-20

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